2SC5553

Silicon NPN triple diffusion mesa type

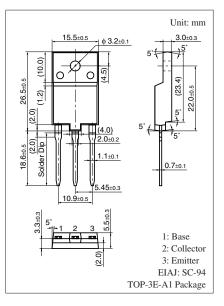
For horizontal deflection output

Features

- High breakdown voltage, and high reliability through the use of a glass passivation layer
- High-speed switching
- Wide safe operation area

Absolute Maximum hattings $T_c = 25 C$								
Parameter	Symbol	Rating	Unit					
Collector-base voltage (Emitter open)	V _{CBO}	1 700	V					
Collector-emitter voltage (E-B short)	V _{CES}	1 700	V					
Collector-emitter voltage (Base open)	V _{CEO}	600	V					
Emitter-base voltage (Collector open)	V _{EBO}	7	V					
Base current	IB	11	А					
Collector current	I _C	22	А					
Peak collector current *	I _{CP}	30	А					
Collector power dissipation	P _C	70	W					
$T_a = 25^{\circ}C$	1	3.5						
Junction temperature	Tj	150	°C					
Storage temperature	T _{stg}	-55 to +150	°C					



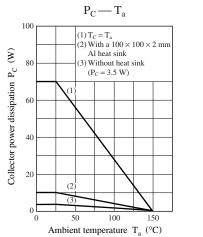


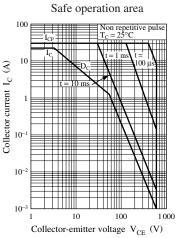
Note) *: Non-repetitive peak collector current

Electrical Characteristics $T_C = 25^{\circ}C \pm 3^{\circ}C$

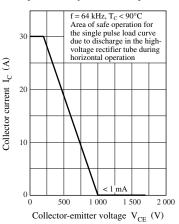
Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 1000$ V, $I_E = 0$			50	μΑ
		$V_{CB} = 1700$ V, $I_E = 0$			1	mA
Emitter-base cutoff current (Collector open)	I _{EBO}	$V_{EB} = 7 V, I_C = 0$			50	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 5 V, I_C = 11 A$	6		12	_
Collector-emitter saturation voltage	V _{CE(sat)}	$I_C = 11 \text{ A}, I_B = 2.75 \text{ A}$			3	V
Base-emitter saturation voltage	V _{BE(sat)}	$I_C = 11 A, I_B = 2.75 A$			1.5	V
Transition frequency	f _T	$V_{CE} = 10 \text{ V}, I_C = 0.1 \text{ A}, f = 0.5 \text{ MHz}$		3		MHz
Storage time	t _{stg}	$I_C = 11$ A, Resistance loaded			3.0	μs
Fall time	t _f	$I_{B1} = 2.75 \text{ A}, I_{B2} = -5.5 \text{ A}$			0.2	μs

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.





Safe operation area (Horizontal operation)



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